

HDI & UHDI

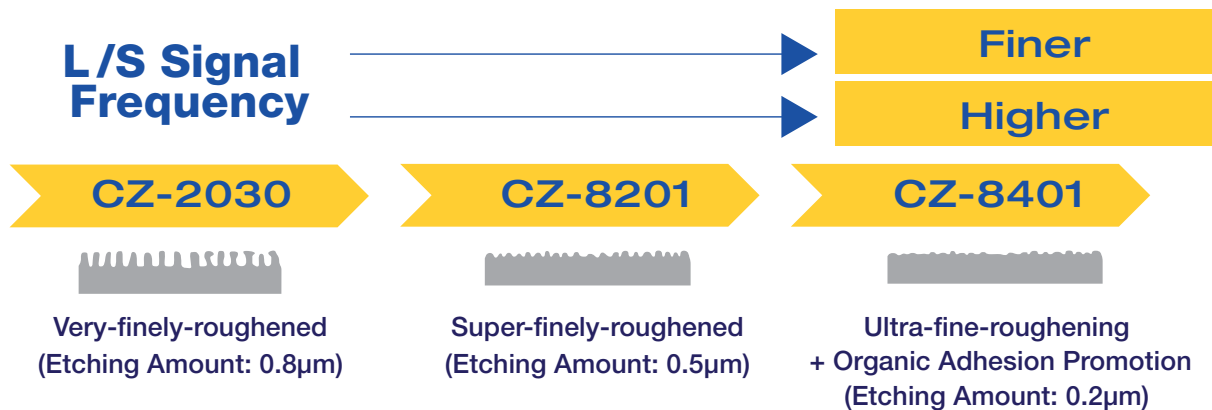
MEC from UYEMURA

is **Already There**

MEC from UYEMURA

Provides Industry's Roadmap for
High Density and Ultra High Density Circuits

Etchbond optimizes copper bonding to resin, dry film or solder mask.



V-BOND 7710 is an $\text{H}_2\text{SO}_4\text{-H}_2\text{O}_2$ -type microetchant with substantial cost and maintenance advantages compared with conventional oxide alternatives. It provides exceptional inner layer adhesion to all resins, including high Tg, HF (halogen-free), and PTFE.

Anisotropic Etching Enhancers including EXE-6722, improve sidewall profiles and enable finer lines and higher yields.

Flash and Differential Etchants for SAP/mSAP provide precise controlled etching and optimize sidewall geometries.

Increasing Etch Rate

QE-7330

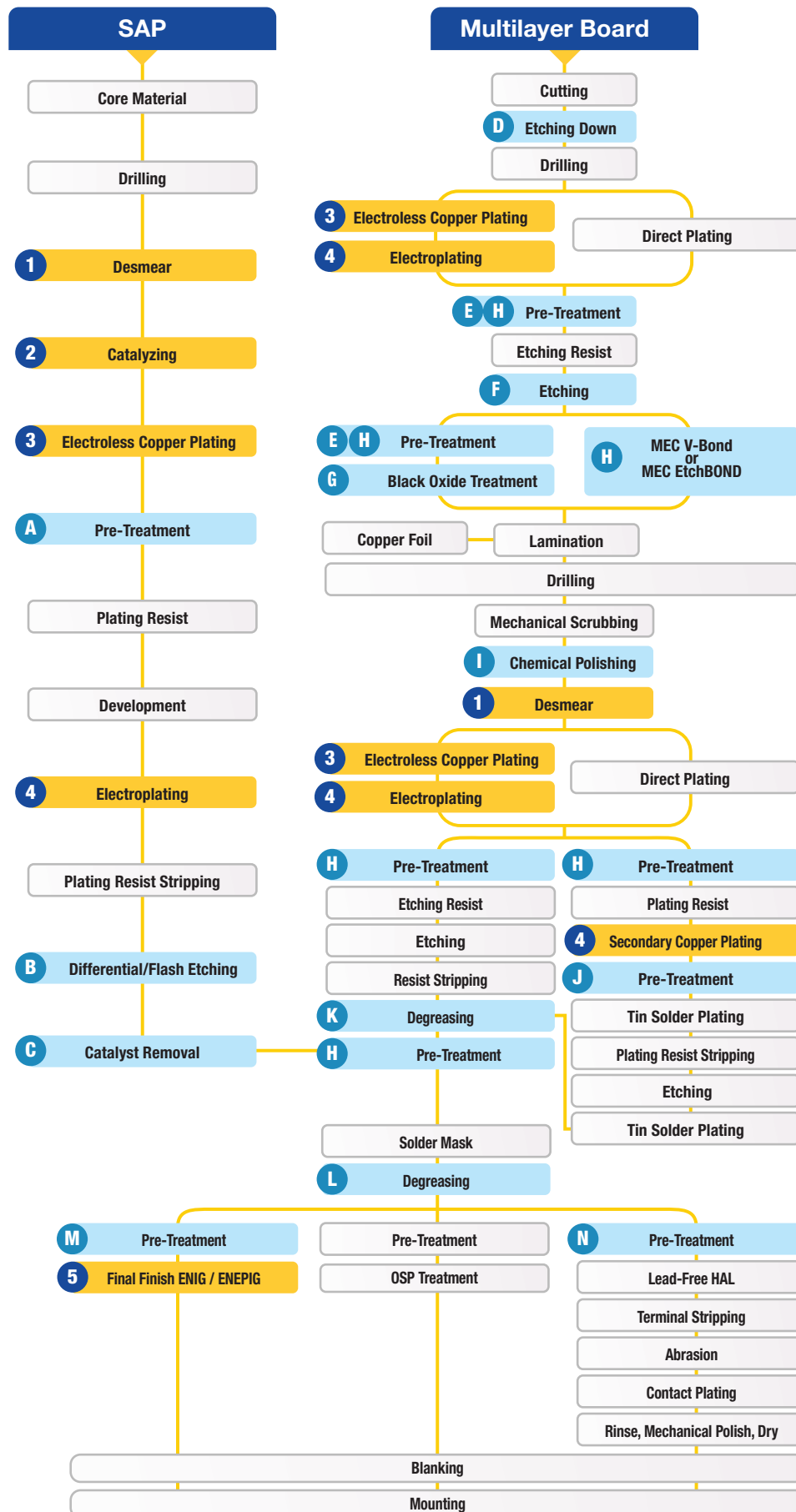
CI-7200

HE-7002

MEC from Uyemura

IC Substrate

Process Chart



Index

UYEMURA PRODUCTS

- 1 APPDES
- 2 ALCUP
- 3 PEA
- 4 THRU-CUP
- 5 MPC/MFD5/TALON/NPR/TWX

MEC PRODUCTS

- A STZ-3100 or STL
- B QE-7330, CI-7200
- C PJ-9720
- D HE-7002A
- E CB-5002
- F EXE SERIES
- G V-BOND B0-7710V
- H CZ-2030, CZ-2050, or CZ-8201 (with CL-8300 or CL-2301)
- I SF-5420
- J CA-91Y, CB-801Y, CB-5620AY, or CA-5342
- K CA-5372 or CA-5342
- L CA-5342
- M CA-5330K or CA-5344
- N CZ-5480



UYEMURA

Corporate Headquarters:

Ph: (909) 466-5635

Tech Center:

Ph: (860) 793-4011

www.uyemura.com

Download the newest
MEC from Uyemura brochure

